PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

Assignment ID: PATI336253

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YuanYuan Yang	06/19/2024
XiaoZhen Li	06/19/2024
MengJiang Xing	06/19/2024
HongYu Yang	06/19/2024
YiFang Zhang	06/19/2024

RECEIVING PARTY DATA

Company Name:	Huzhou Ceramic-Chip Electronic Technology Co., Ltd.
Street Address:	Building 23, Zhigu Industrial Park
Internal Address:	No.1558 Dongpo Road, Kangshan Street
City:	Huzhou City
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18761318

CORRESPONDENCE DATA

Fax Number: 9052869781

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 4805614607
Email: info@macauip.com
Correspondent Name: LEONG C. LEI
Address Line 1: PMB # 1008
Address Line 2: 1839 YGNACIO VALLEY ROAD
Address Line 4: WALNUT CREEK, CALIFORNIA 94598

ATTORNEY DOCKET NUMBER:	24041THXT-0041-FPZZ28691
NAME OF SUBMITTER:	Sheelina Chiang
SIGNATURE:	Sheelina Chiang
DATE SIGNED:	07/02/2024
Total Attachments: 2	

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ASSIGNMENT

WHEREAS, ASSIGNOR,

1. YuanYuan Yang, residing at No. 88 Hangchangqiao North Road,Residential Group, Longxi Street, Wuxing District, Huzhou City, Zhejiang Province, China
2. XiaoZhen Li, residing at No. 2 Puxin Road, Guandu District, Kunming City, Yunnan Province, China
3. MengJiang Xing, residing at Kunming University of Technology, No. 2, Yuhua District, Chenggong District, Kunming, Yunnan, China
4. HongYu Yang, residing at South Gate of Xi'an University of Electronic Science and Technology Community, No. 2 Taibai South Road, Yanta District, Xi'an City, Shaanxi Province, China
5. YiFang Zhang, residing at No.7, Gate 2, 3rd Floor, No.15 Haidian Ganggou Courtyard, Haidian District, Beijing, China

(collectively referred to as ASSIGNOR),

owns all right, title and interest in the invention as disclosed and/or claimed in the U.S. patent application, entitled PREPARATION METHOD FOR MICROWAVE DIELECTRIC RESONATOR WITH LAMINATED STRUCTURE , which

[x] is concurrently filed herewith; or

[ ] was previously filed on ____________ with Application No. __________________;

AND, ASSIGNEE,

1. Huzhou Ceramic-Chip Electronic Technology Co., Ltd., having offices at Building 23, Zhigu Industrial Park, No.1558 Dongpo Road, Kangshan Street, Huzhou City, Zhejiang Province, China

(collectively referred to as ASSIGNEE),

desires to own ASSIGNOR's entire right, title, and interest in and to the invention and in and to the above-described U.S. patent application.

NOW THEREFORE, be it known for one U.S. dollar (US$1) and other good and valuable consideration, receipt of which is hereby acknowledged, ASSIGNOR hereby assigns, transfers and sets over to ASSIGNEE, its lawful successors and assigns, ASSIGNOR's entire right, title, and interest in and to the invention and the U.S. patent application as described above, and other patent application, including but not limited to any continuing application, directed or to be directed to the invention, and all Letters Patent of the United States that may be granted therein, and all reissues, reexaminations, and extensions thereof; and all rights to claim priority on the basis of such application; and all applications for Letters Patent that may be filed for the invention in any other country and all Letters Patent that may be granted on the invention in any other country, and all extensions, renewals, reissues thereof; and ASSIGNOR hereby authorizes and requests the Commissioner for Patents of the United States and any official of any other country whose duty is to issue patents on patent applications, to issue all Letters Patent for this invention to ASSIGNEE, its successors and assigns, in accordance with the terms of this Assignment;

AND, ASSIGNOR HEREBY further covenants that ASSINOR has the full right to convey the interest assigned by this Assignment, ASSIGNOR will take all action and execute all documents necessary to perfect the interest assigned hereby, and ASSIGNOR has not executed and will not execute any agreement in conflict with this Assignment;

AND, ASSIGNOR HEREBY further covenants and agrees that ASSIGNOR will, without further consideration, communicate with ASSIGNEE, its successors and assigns, any facts known to ASSIGNOR respecting the invention and testify in any legal proceeding, sign all lawful papers that may be necessary or desirable to perfect the title to the invention in said ASSIGNEE, its successors and assigns, execute all rightful oaths, and generally do everything possible to aid ASSIGNEE, its successors and assigns, to prosecute any patent application described above and obtain and enforce proper patent protection for the invention in the United States and in any other country, it being understood that any expense incident to the execution of such papers shall be borne by ASSIGNEE, its successors and assigns.

IN TESTIMONY WHEREOF, ASSIGNOR has executed his Assignment the day and year below written.

杨圆圆
YuanYuan Yang
Date: 2024-06-19

李小珍
XiaoZhen Li
Date: 2024-06-19

邢孟江
MengJiang Xing
Date: 2024-06-19

杨鸿宇
HongYu Yang
Date: 2024-06-19

张一昉
YiFang Zhang
Date: 2024-06-19